モータ・ドライバ: 熱管理

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熱設計とは

ABSOLUTE MAXIMUM RATINGS (1)

Supply voltage (V_{IN}) .....-0.3V to +45V
VCP voltage (V_{CP}).....V_{IN} to V_{IN} + 6.5V
V_{OUTx} .....-0.3V to V_{IN} + 0.3V
PGND1, PGND2 to AGND.....-0.3V to +0.3V
All other pins to AGND.....-0.3V to +6.5V
Continuous power dissipation (T_A = 25°C) (2)
.....2.6W
Junction temperature (T_J) .....150°C
Lead temperature .....260°C
Storage temperature..... -65°C to +150°C

1) Exceeding these ratings may damage the device.

Recommended Operating Conditions (3)

Supply voltage (V_{IN}) .....4V to 40V
Operating junction temp (T_J).... -40°C to +125°C

3) The device is not guaranteed to function outside of its operating conditions.

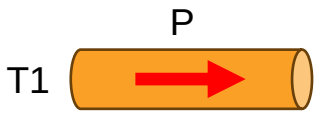
Thermal Metrics (4)

θ_{JA} (junction-to-ambient).....44.3°C/W
θ_{JC_TOP} (junction-to-case top).....37.5°C/W
Ψ_{JT} (junction-to-top).....1.1°C/W

4) According to JEDEC JESD51-2/-5/-7/-8/-14.

熱の伝わり方

✓ 熱抵抗 θ



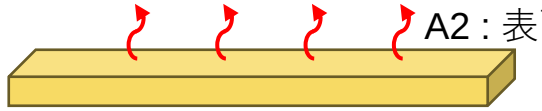
$$\theta = \frac{T1 - T2}{P} \ [℃/W]$$

熱	熱流量 P [W]	温度差 dT [℃]	熱抵抗 θ [℃/W]
電気	電流 I [A]	電圧差 dV [V]	電気抵抗 R [Ω]

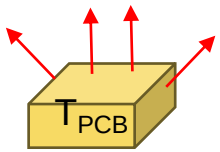
✓ 放熱経路

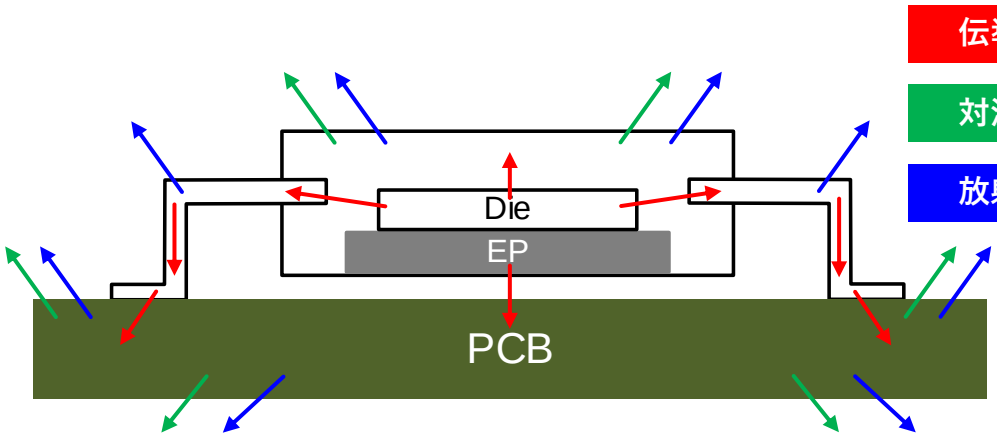
・伝導　$\theta_{CD} = \frac{L}{A_1 \times \lambda}$

・対流　$\theta_{CV} = \frac{1}{A_2 \times h}$



・放射　$\theta_{RD} = \frac{1}{A_3 \times \sigma \times \varepsilon \times ({T_{PCB}}^4 - {T_{AMB}}^4)}$

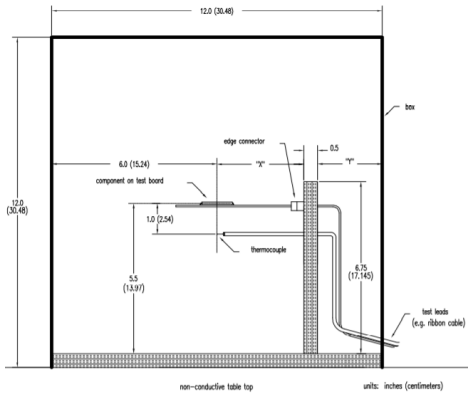


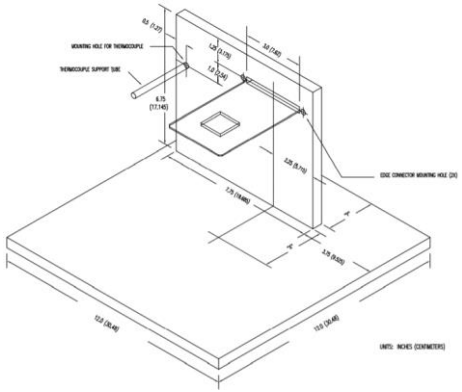


熱伝導経路

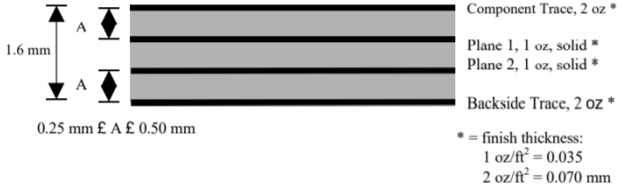
λ: 熱伝導率、 h: 対流熱伝導率、 σ: ボルツマン定数、 ε: 放射係数（材料固有の値）

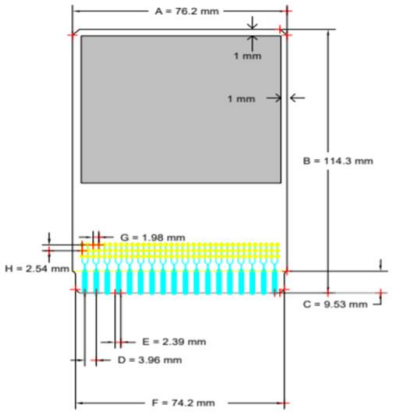
JEDEC JESD51 試験環境



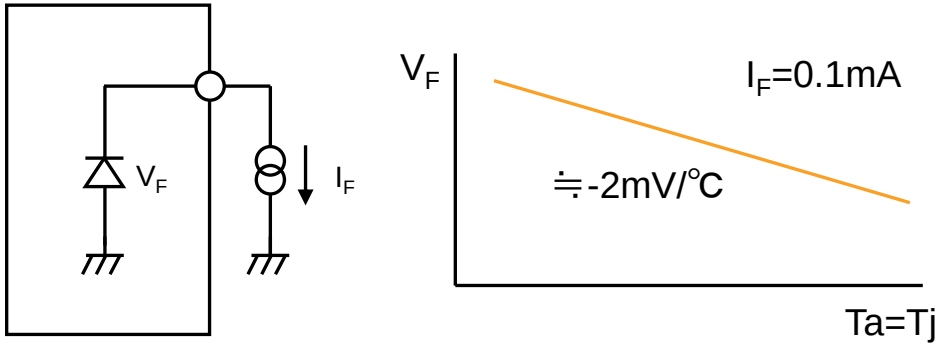


測定環境





PCB

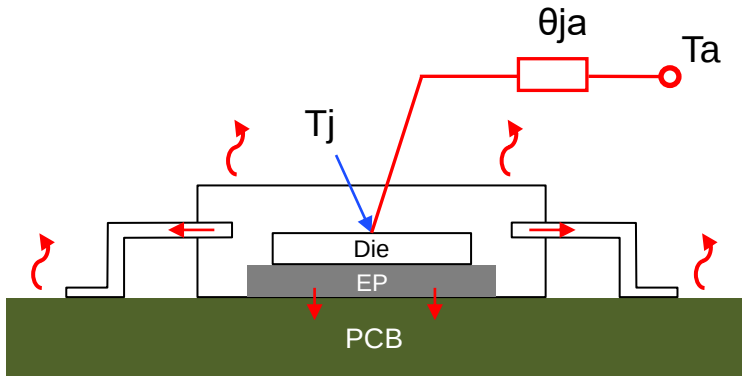


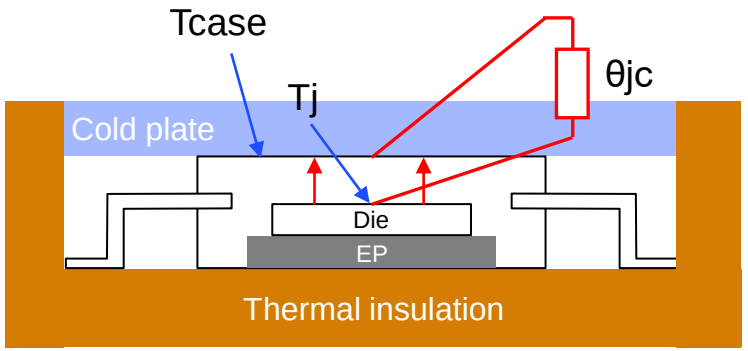
測定の事前準備

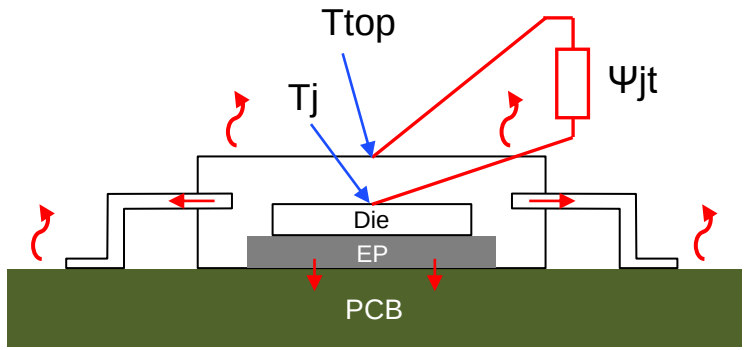
熱抵抗の測定

Thermal Metrics

θ_{JA} (junction-to-ambient).....44.3°C/W
θ_{JC_TOP} (junction-to-case top).....37.5°C/W
Ψ_{JT} (junction-to-top).....1.1°C/W







$$\theta_{ja} = \frac{Tj - Ta}{P} \ [℃/W]$$

$$\theta_{jc} = \frac{Tj - Tcase}{P} \ [℃/W]$$

$$\psi_{jt} = \frac{Tj - Ttop}{P} \ [℃/W]$$

θja

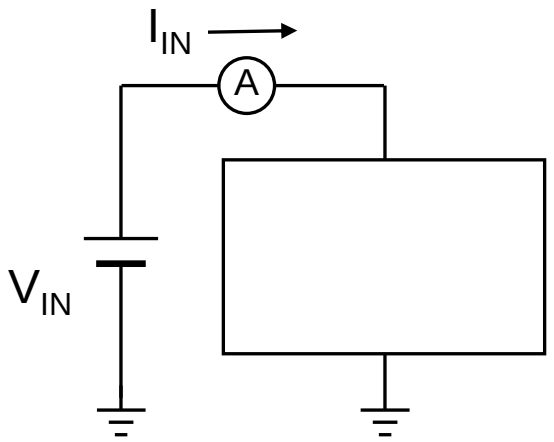
θjc

Ψjt

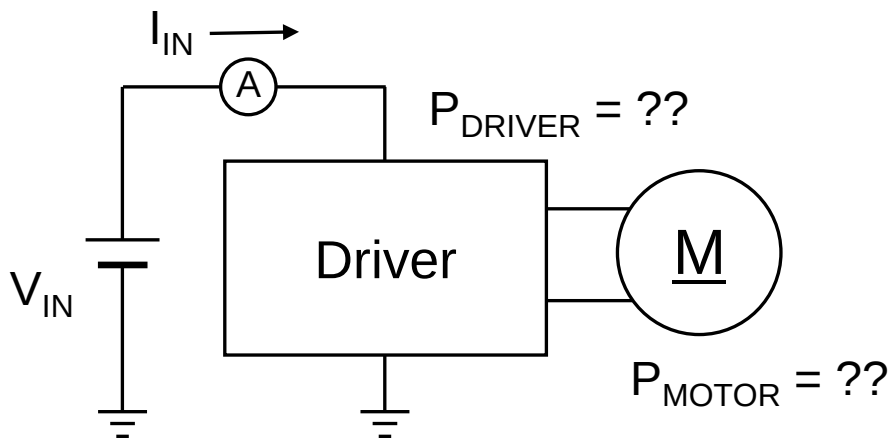
$$Tj = \theta_{ja} \times P + Ta \ [℃]$$

$$Tj = \psi_{jt} \times P + Ttop \ [℃]$$

モータ・ドライバの消費電力

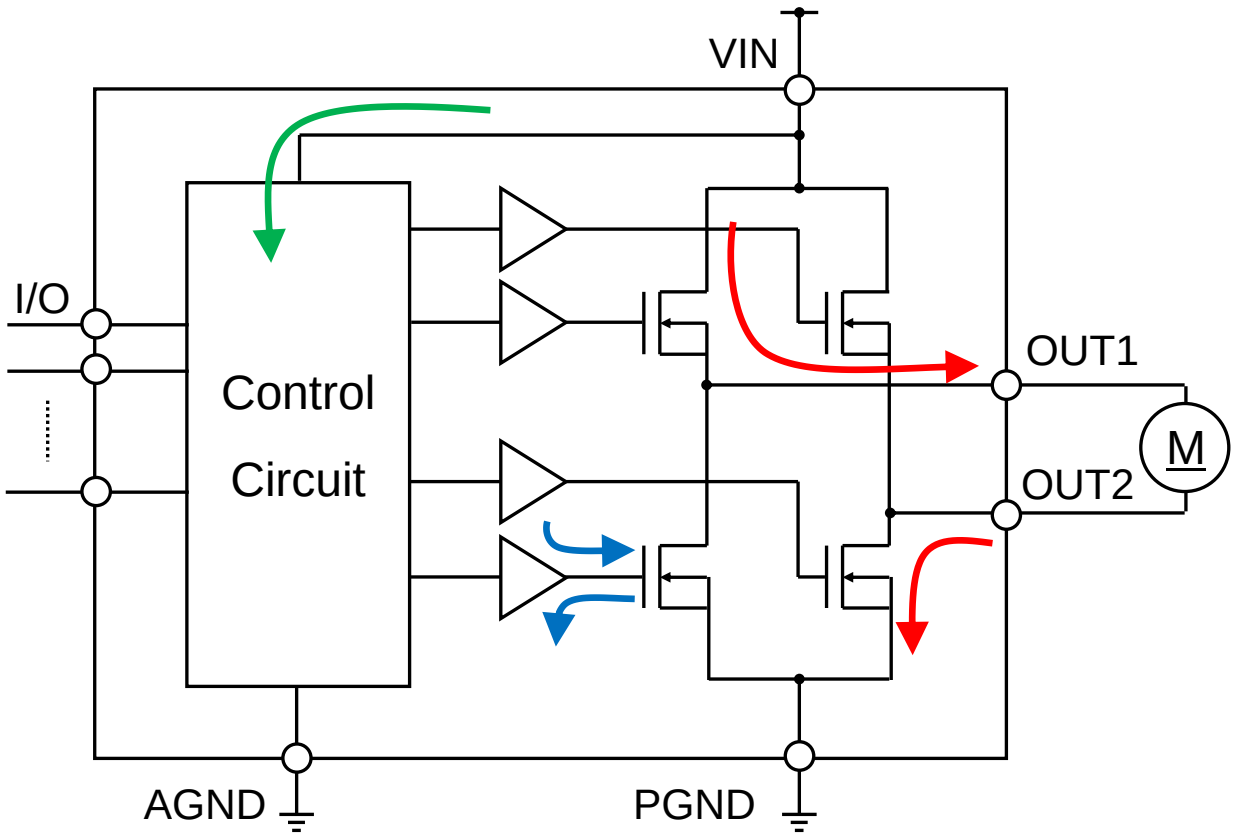


$$P = V_{IN} \times I_{IN}$$



$$P = V_{IN} \times I_{IN} = P_{DRIVER} + P_{MOTOR}$$

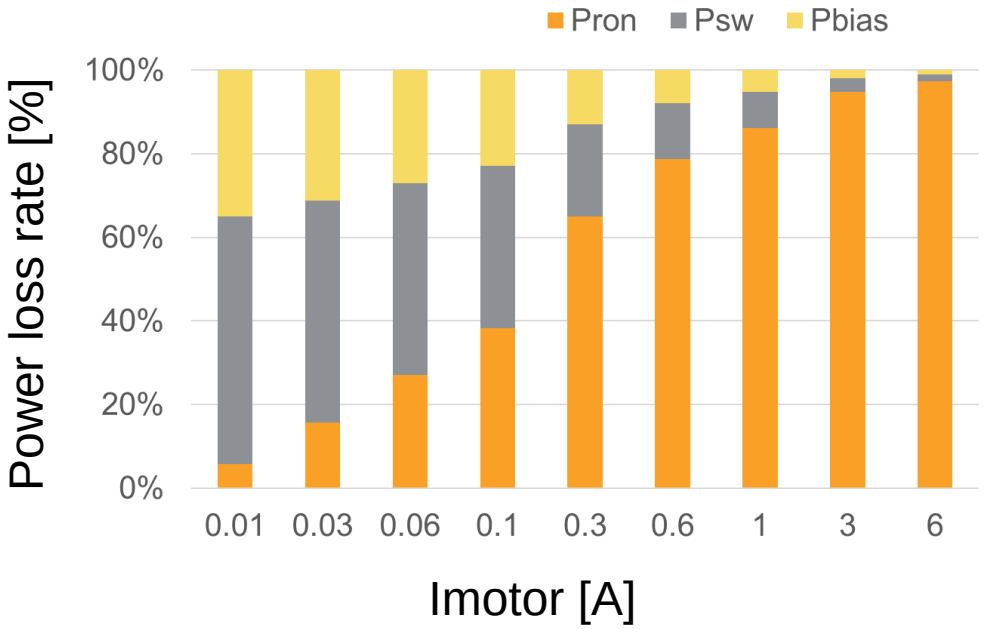
モータ・ドライバの消費電力



$$P_{Bias} = Vin \times Icc$$

$$P_{SW} = V^2 \times f \times Ciss$$

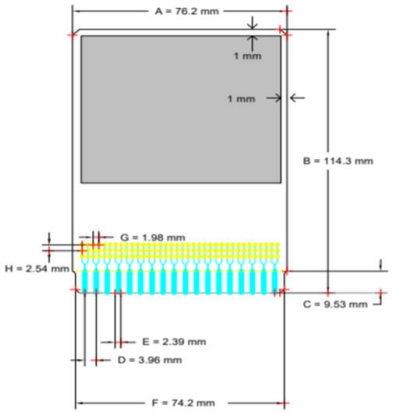
$$P_{Ron} = (RonH + RonL) \times Imotor^2$$

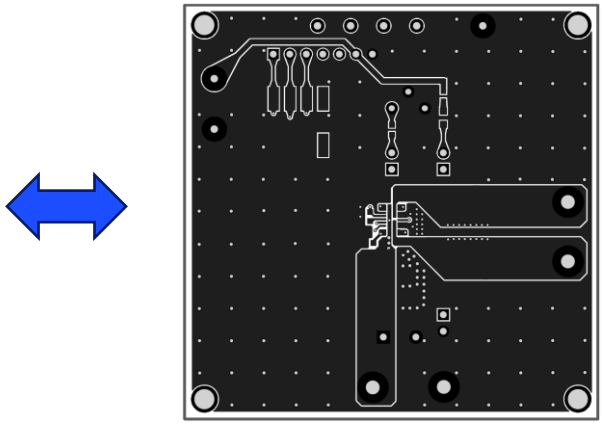


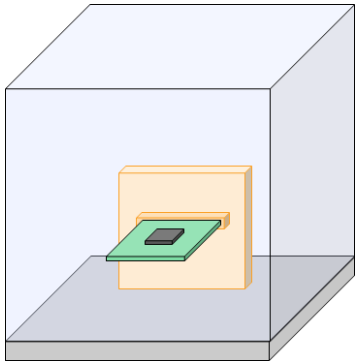
Tjの算出

$$Tj = \theta_{ja} \times P + Ta \ [℃]$$

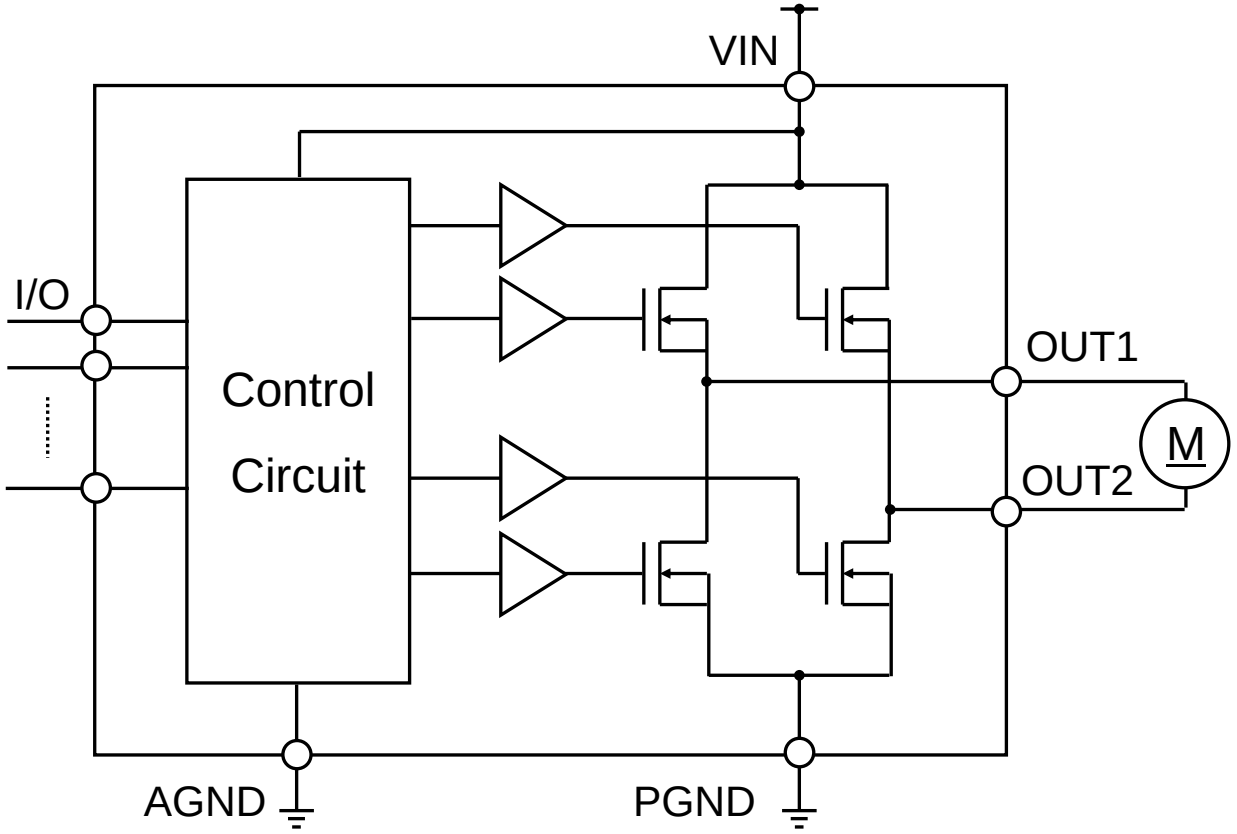
$$Tj = \psi_{jt} \times P + Ttop \ [℃]$$

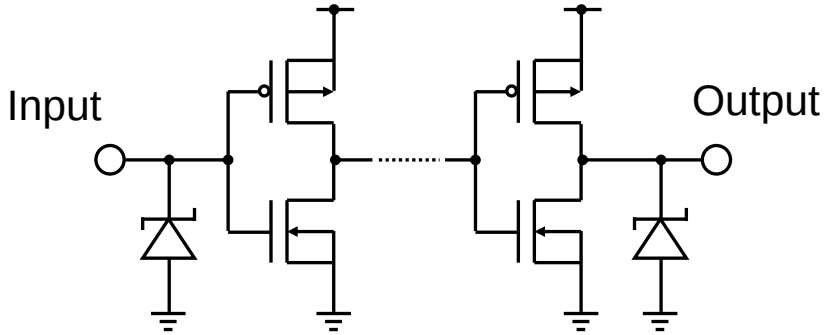




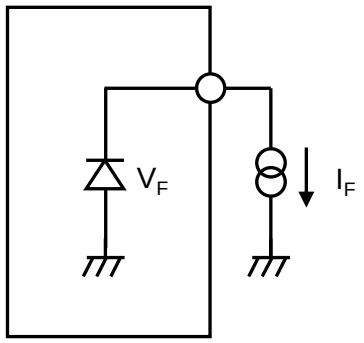


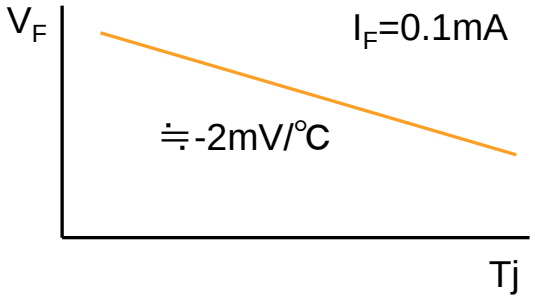
Tjの実測



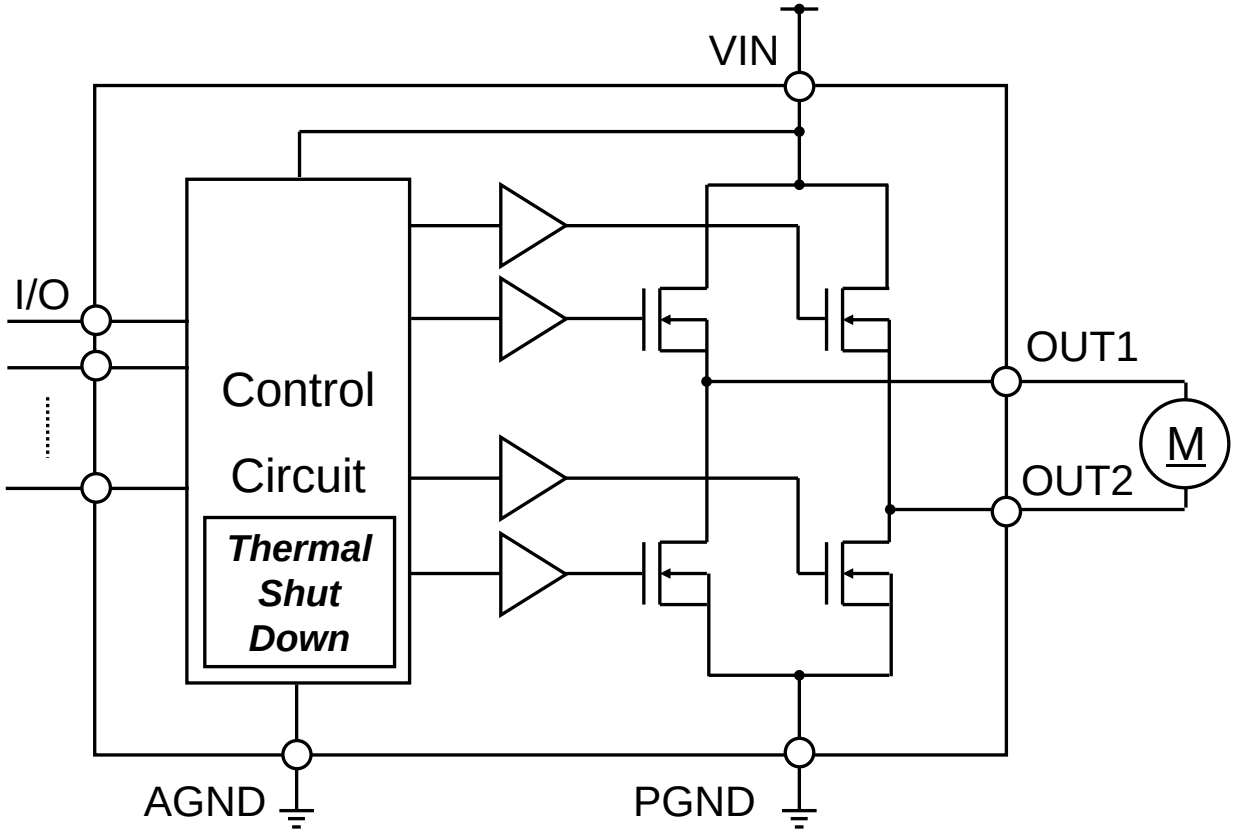


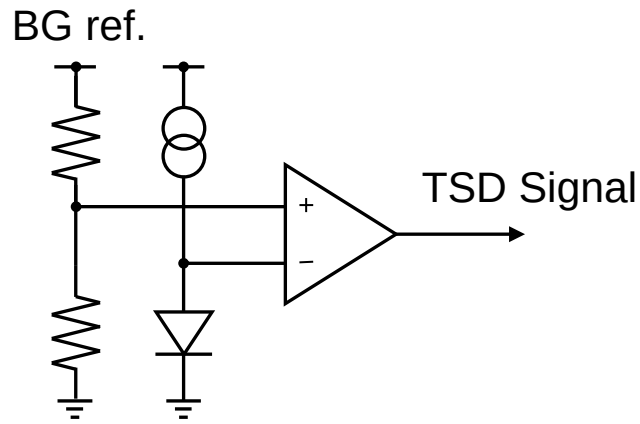
I/O Circuit





Tjの実測



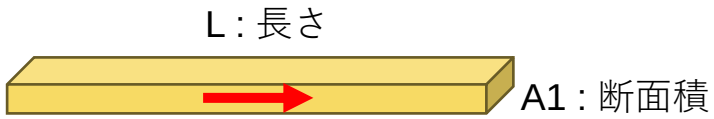


TSD Circuit

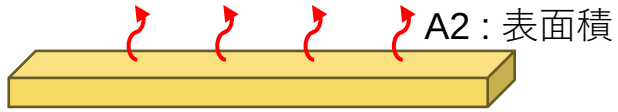
Tjを低減するPCB設計

✓ 放熱経路

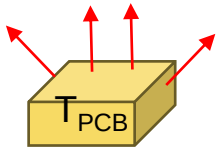
・伝導　$\theta_{CD} = \frac{L}{A_1 \times \lambda}$



・対流　$\theta_{CV} = \frac{1}{A_2 \times h}$



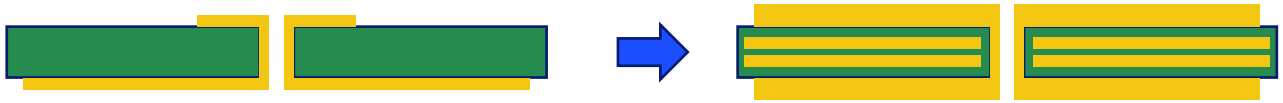
・放射　$\theta_{RD} = \frac{1}{A_3 \times \sigma \times \varepsilon \times ({T_{PCB}}^4 - {T_{AMB}}^4)}$



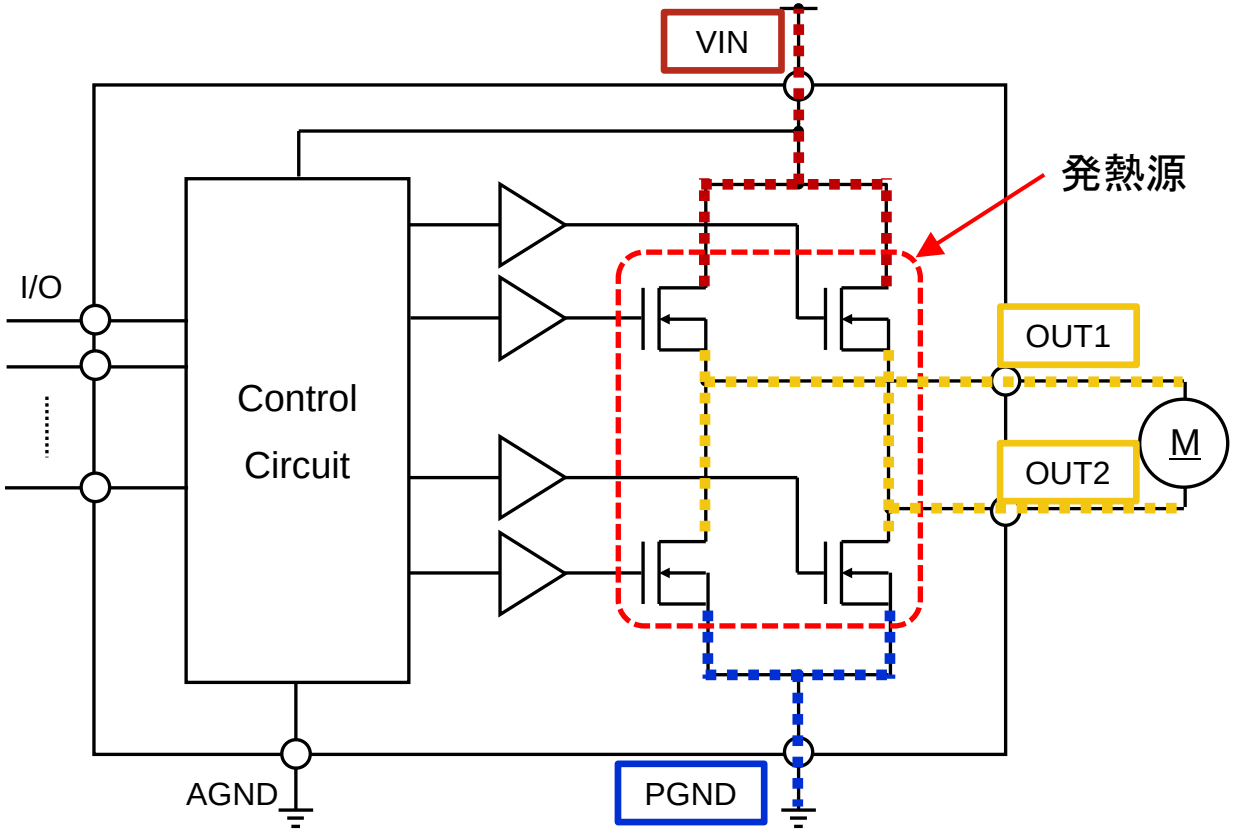
A3: 表面積

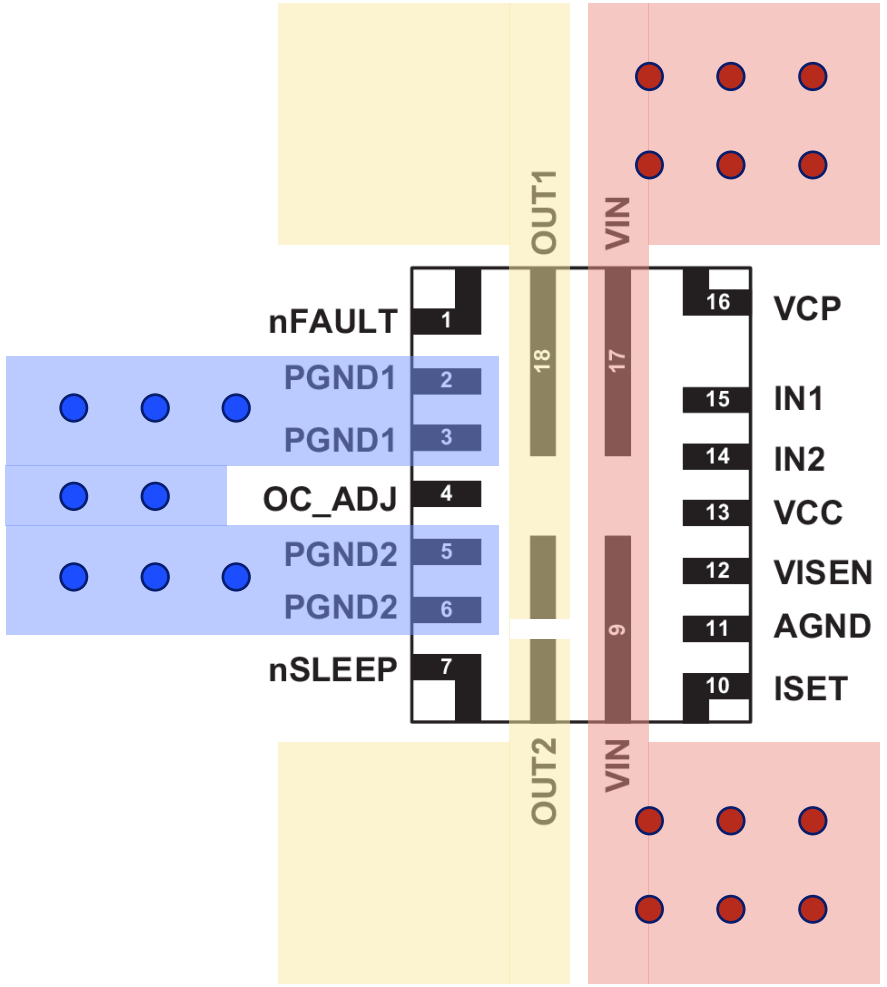
材料	熱伝導率 λ [W/mK]
銅	419
金	295
シリコン	162
半田	49
FR4	0.25

T=20℃, 1013.25hPa



PCBレイアウト例


VIN
発熱源
I/O
Control
Circuit
OUT1
OUT2
M
AGND
PGND


OUT1
VIN
nFAULT
1
PGND1
2
PGND1
3
OC_ADJ
4
PGND2
5
PGND2
6
nSLEEP
7
18
17
9
16
VCP
15
IN1
14
IN2
13
VCC
12
VISEN
11
AGND
10
ISET
OUT2
VIN

サマリー

✓ 熱設計の重要性

✓ Tjを正しく把握
- θja、Ψjtを用いた算出
- ダイオード / サーマルシャットダウン機能を用いた測定

✓ 効果的なPCB設計
- 伝熱を理解したPCBレイアウト